

La/Al-doped ZrO₂ Thin-Film Resistive Random Access Memory Devices by Sol-gel Method for Transparent Solid-State Circuit Systems

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Abstract

A sol-gel method with doping technology is conducted in fabricating fully transparent resistive random access memory (TRRAM) devices with configuration of FTO/doped ZrO₂/ITO. Sol-gel-derived lanthanum (La) or aluminum (Al) doped zirconium dioxide (ZrO₂) film and indium tin oxide (ITO) film were deposited on fluorine tin oxide (FTO) glass substrate and resistive switching (RS) layer successively. Compared with our previous work, doped ZrO₂ enhanced the RS uniformity and retention, indicating great application potential for transparent electronic system.

1. Introduction

Transparent solid-state circuit systems, regarding as the next-generation circuits, have been widely studied over the past years[1]. As crucial parts, traditional memory modules tend to be difficult in realizing transparency. Oxide-based resistive random access memory (RRAM), with outstanding electronic performances, reveals its feasibility. Although traditional fabricating processes, such as chemical vapor deposition, atomic layer deposition and sputtering[2] could also fabricate thin-film, sol-gel method highlights itself with low cost and large-area manufacturing possibility. In our previous work, pure ZrO₂ thin-film based RRAM suffered from poor uniformity, which remains to be settled. A doping method applied in sol-gel technology for oxide-based RRAM proves to be possible in improving the uniformity[3], and retention enhancement had also been detected.

In this paper, we fabricated La/Al-doped ZrO₂ transparent RRAM, with a configuration of FTO/doped ZrO₂/ITO under solution process. Thin-film layers including resistive switching (RS) layer and indium tin oxide (ITO) films, being as top-electrode layer, were spin-coated on fluorine tin oxide (FTO) glass substrate by sol-gel method successively. Electronic characteristics of resistive switching were investigated.

2. Experiment

A schematic view of FTO/doped ZrO₂/ITO TRRAM is shown in fig.1 a), and fig.1 b) shows the fabricated device placed on logo. A doped ZrO₂ layer with a thickness of 20 nm was deposited on FTO glass substrate. The process of fabricating RS layer was presented in fig.2(a), where zirconium n-butoxide and lanthanum nitrate hydrate or aluminum nitrate nonahydrate were chosen as precursor materials[4]. After mixing and stirring zirconium n-butoxide solution with anhydrous ethanol, the doping salts was

added. Acetylacetone and acetic acid, selected as stabilizer, were dipped in the solution above successively. The molar ratio of zirconium butoxide : lanthanum/aluminum nitrate: anhydrous ethanol :acetic acid is 50:1:800:200[5], which means atomic ratio of Al or La to Zr is 2%. Top electrodes with a thickness of 20nm shown in fig.2(b) were fabricated on RS layer. Indium nitrate hydrate and tin chloride pentahydrate were selected as precursor materials[6]. Acetylacetone was acting as stabilizing material. Usually, the molar ratio of indium : tin : acetylacetone is 10:1:30. Being spin-coated and heated, devices were followed by annealing at 500 °C for 2h. Current-voltage measurements were conducted by KEITHLEY 4200 semiconductor parameter analyzer.

3. Results

The RS behaviors of this transparent RRAM were tested, as illustrated in fig.3, where I-V curves of 1st, 10th and 100th were presented. Forming voltage of 8.86V(La) and 7.89V(Al) was observed when turned from initial resistance state (IRS) to low resistance state (LRS). The device turned from LRS to high resistance state(HRS) while negative voltage sweeping was applied. Subsequent voltage sweeping mode was repeated by 0V → 3V → 0V → 3V. Current compliance (CC) of 10mA was fixed. After switching for 100 times, the distribution of V_{set} and V_{reset} was arranged, as manifested in fig.4 comparing with un-doped ones[7]. Operation voltage could be less than 3V, as Table I reveals the characteristics of V_{set} and V_{reset} for both doped devices.

Compared with our previous work[7], after doping La/Al into ZrO₂, the memory window was dropped. As illustrated in fig.5, after switching for more than 100 cycles, the resistance HRS/LRS ratio was more than 5 with no obvious degradation. The RS uniformity was improved like what compares in Table II and fig.5. The retention time of La-ZrO₂ and Al-ZrO₂ based devices was more than 4000s and 3000s respectively at room temperature as shown in fig.6, which was improved when comparing with un-doped ZrO₂ sol-RRAM devices with a retention time of 1000s. This result indicated the potential of doped ZrO₂ for storing data.

The reduction of HRS/LRS ratio and uniformity improvement may attribute to the decrease of forming energy of oxygen vacancy (V_o) caused by trivalent dopant, since V_o mostly formed near dopants in stabilizing the formation of V_o conducting filaments. The reduction of resistance is also related to trivalent dopant. The result is in accordance with our previous work[3].

4. Conclusions

A doping technology for oxide-based TRRAM by sol-gel method is presented. Top electrode layer and RS layer were fabricated by spin-coating. Fully transparency and bipolar RS behaviors were obtained. Programming current is less than 10 mA and operation voltage is less than 3V. Since doped ZrO₂ improved the RS uniformity and retention, this TRRAM has potential applications in large area and transparent electronic system.

Acknowledgments

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References

- [1] J. F. Wager, "Transparent Electronics", *Science*, vol. 300 No.5623, p. 1245, (May 2003).
- [2] Kim, Areum, et al. "All solution-processed, fully transparent resistive memory devices." *ACS applied materials & interfaces* 3.11 (2011): 4525-4530.
- [3] Zhang, Haowei, et al. "Ionic doping effect in ZrO₂ resistive switching memory." *Applied Physics Letters* 96.12 (2010): 123502.

- [4] Bing, Sun, et al. "Improved Resistive Switching Characteristics of Ag-Doped ZrO₂ Films Fabricated by Sol-Gel Process." *Chinese Physics Letters* 25.6 (2008): 2187.
- [5] Wu, Jeffrey Chi-Sheng, and Li-Chuen Cheng. "An improved synthesis of ultrafiltration zirconia membranes via the sol-gel route using alkoxide precursor." *Journal of Membrane Science* 167.2 (2000): 253-261.
- [6] Su, C., et al. "Preparation of ITO thin films by sol-gel process and their characterizations." *Synthetic Metals* 153.1-3 (2005): 9-12.
- [7] Wang, Yiran, et al. "Solution Processed Resistive Random Access Memory Devices for Transparent Solid-State Circuit Systems." *MRS Proceedings*. Vol. 1633. Cambridge University Press, (2014).

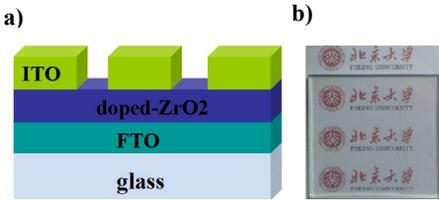


Fig.1 a) Structure of sol-gel based ITO/doped-ZrO₂/FTO TRRAM. b) Photograph of fabricated device.

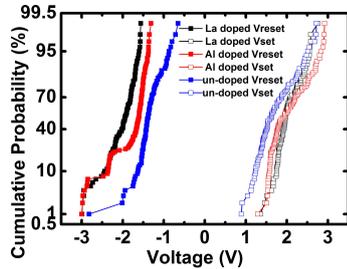


Fig. 4 V_{set} and V_{reset} distribution characteristics for 100 cycles.

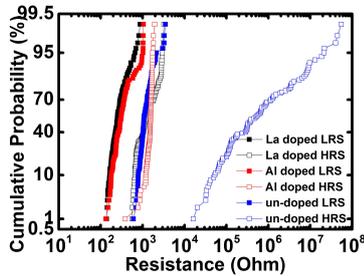


Fig.5 Resistance distribution contrast after 100 cyclings. The doping effect proves improvement in uniformity.

Table II. Standard deviation of HRS and LRS for La-doped, Al-doped and un-doped ZrO₂ based TRRAM

	La	Al	un-doped [9]
σ_{HRS}	828.37	242.00	10317848.75
σ_{LRS}	167.24	241.85	638.65

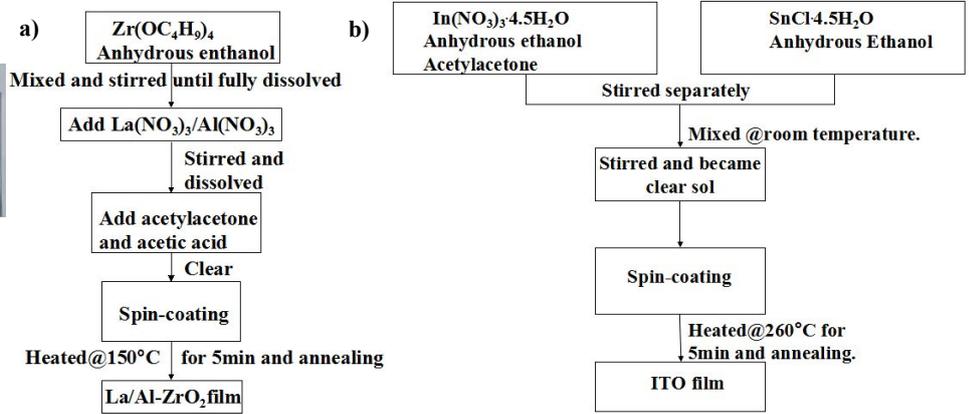


Fig.2 Preparing steps by sol-gel method of a)La-ZrO₂ or Al-ZrO₂ films and b)ITO films.

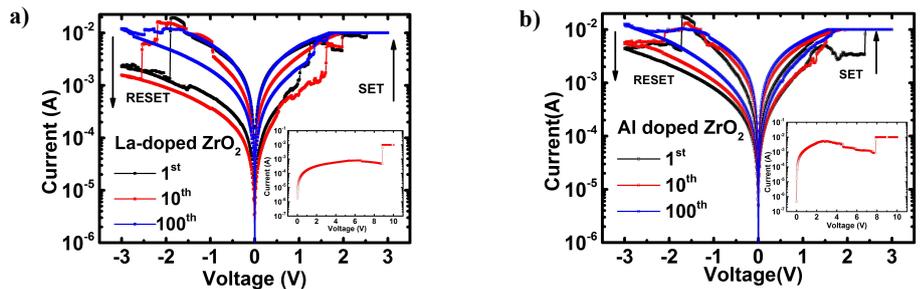


Fig.3 I-V characteristics of a)La-ZrO₂ b)Al-ZrO₂ based TRRAM at 1st, 10th, and 100th cycle. The inset shows the forming process for each case.

Table I. V_{set} and V_{reset} characteristics for La-doped and Al-doped ZrO₂ based TRRAM.

	range /V	σ /V	μ /V
La-doped V _{set}	1.4 to 2.9	0.29	2.03
La-doped V _{reset}	-1.5to- 2.9	0.33	-2.01
Al-doped V _{set}	1.3 to 2.9	0.42	2.02
Al-doped V _{reset}	-1.2 to -3	0.43	-1.78

σ :standard deviation
 μ :arithmetic mean value

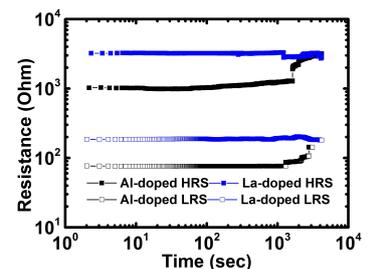


Fig. 6 Retention time of La-doped and Al-doped ZrO₂ based TRRAM for more than 4000s and 3000s.